

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

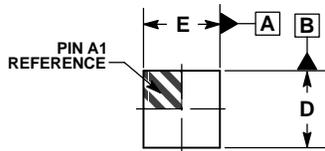
ON Semiconductor®



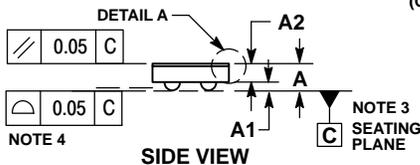
SCALE 4:1

WLCSP4, 0.84x0.84
CASE 567PC
ISSUE A

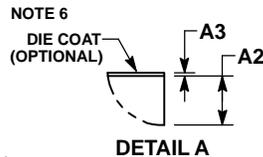
DATE 30 MAY 2017



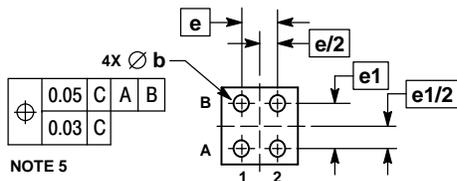
TOP VIEW



SIDE VIEW

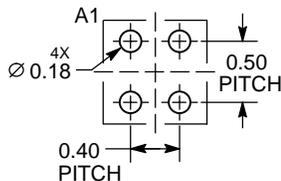


DETAIL A



BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. BACKSIDE COATING IS OPTIONAL.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	---	---	0.30
A1	0.08	0.10	0.12
A2	0.15 REF		
A3	0.025 REF		
b	0.16	0.18	0.20
D	0.81	0.84	0.87
E	0.81	0.84	0.87
e	0.40 BSC		
e1	0.50 BSC		

GENERIC MARKING DIAGRAM*



- X = Specific Device Code
- Y = Year
- W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WLCSP4, 0.84X0.84	PAGE 1 OF 2

